

Time is of the essence

Nikhef



Fast Timing

Working on Detector R&D

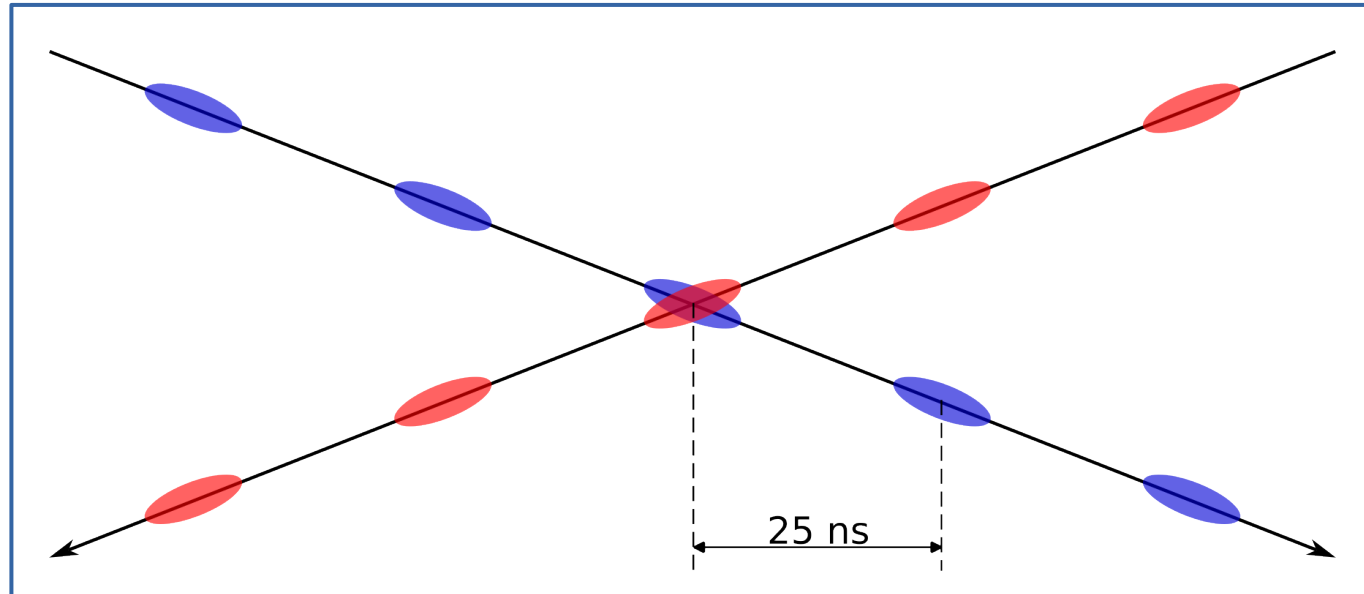


Fast timing, past

- Timing for Particle physics experiments was *ignored* for a long time
- Timing of currently installed LHC detectors
 - Bunch crossings need to be separable
 - 25 ns time resolution sufficient

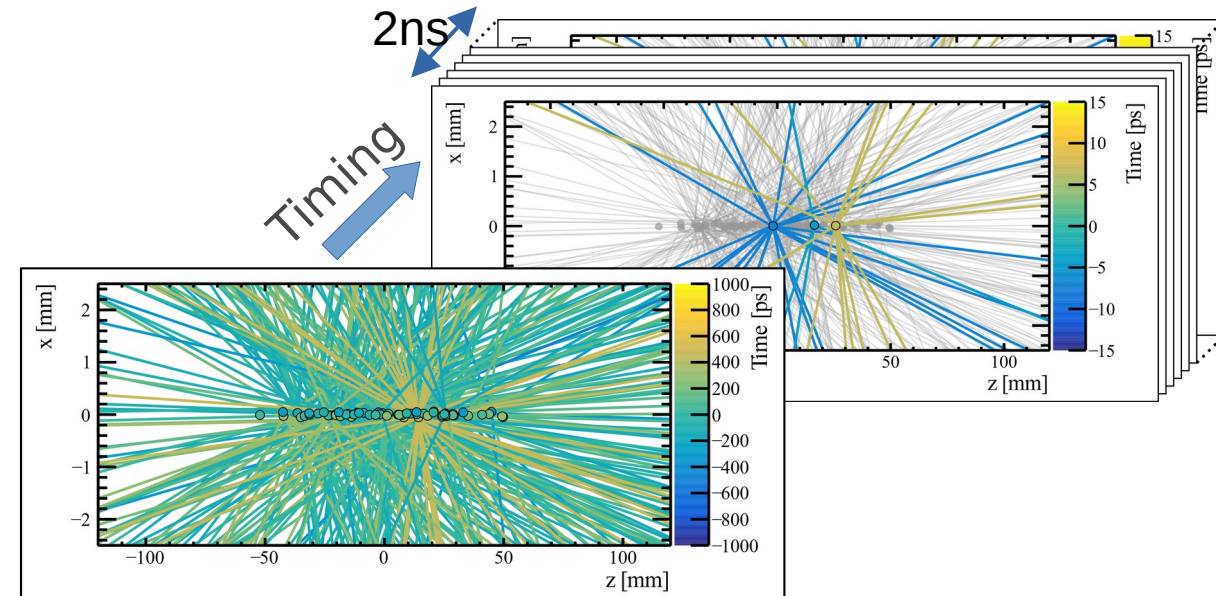
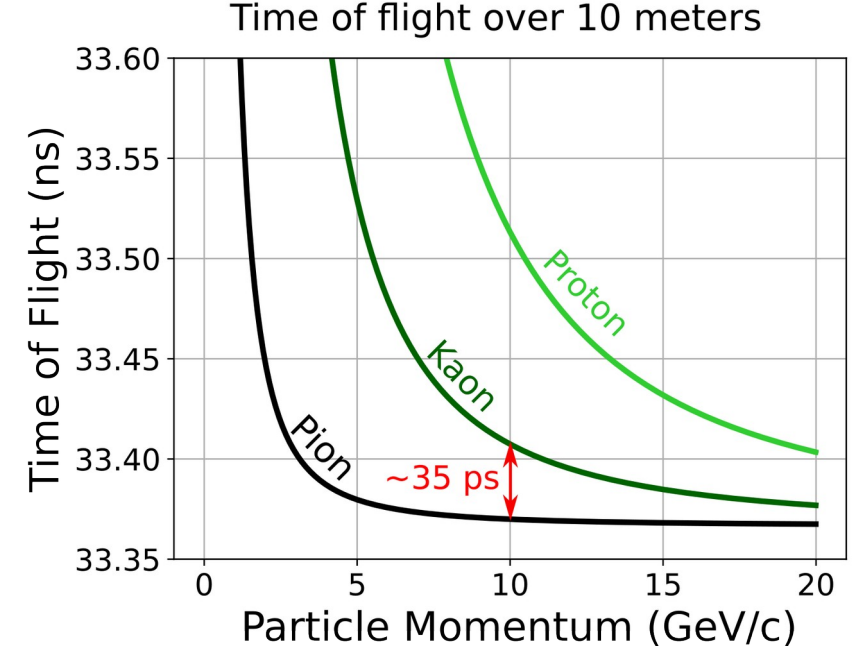
Tab.: Specifications of Timepix3 and VeloPix. Taken from LHCb velo upgrade TDR (2013)

Specification	Timepix3	VeloPix
pixel dimension	$55 \times 55 \mu\text{m}^2$	$55 \times 55 \mu\text{m}^2$
matrix size	256×256	256×256
timewalk	< 25 ns	< 25 ns
Time over Threshold range	10 bit	6 bit (calibration mode only)
leakage current compensation (per pixel)	20 nA	20 nA
Time stamp resolution	1.6 ns	25 ns



Fast timing, future

- Time as an important parameter to embed in the analysis
 - Time of Flight based particle identification
 - Further physics analysis
 - 4D-Tracking
 - Improved tracking performance
 - Reduced tracking complexity
- **All require $O(30 \text{ ps})$ time resolution**



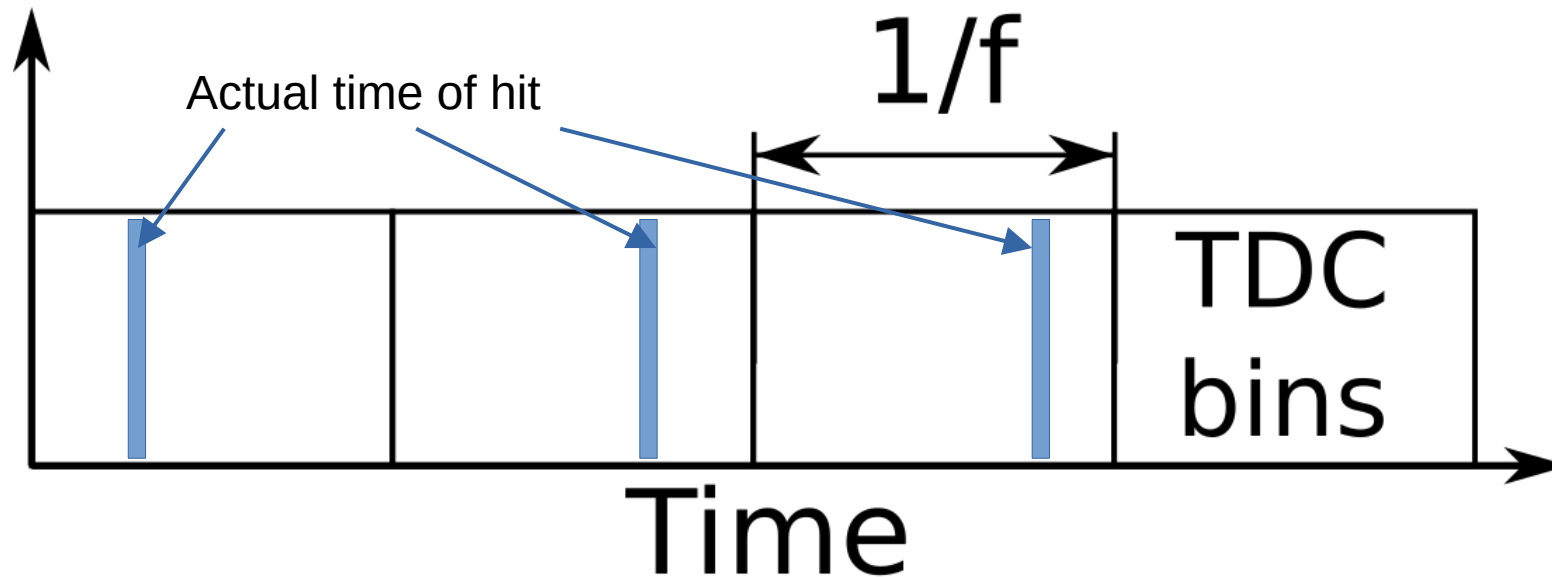
© LHCb collaboration

Contributions to time resolution

$$\sigma_t^2 = \sigma_{\text{clock-global}}^2 + \sigma_{\text{clock-on-chip}}^2 + \sigma_{\text{TDC}}^2 + \dots$$

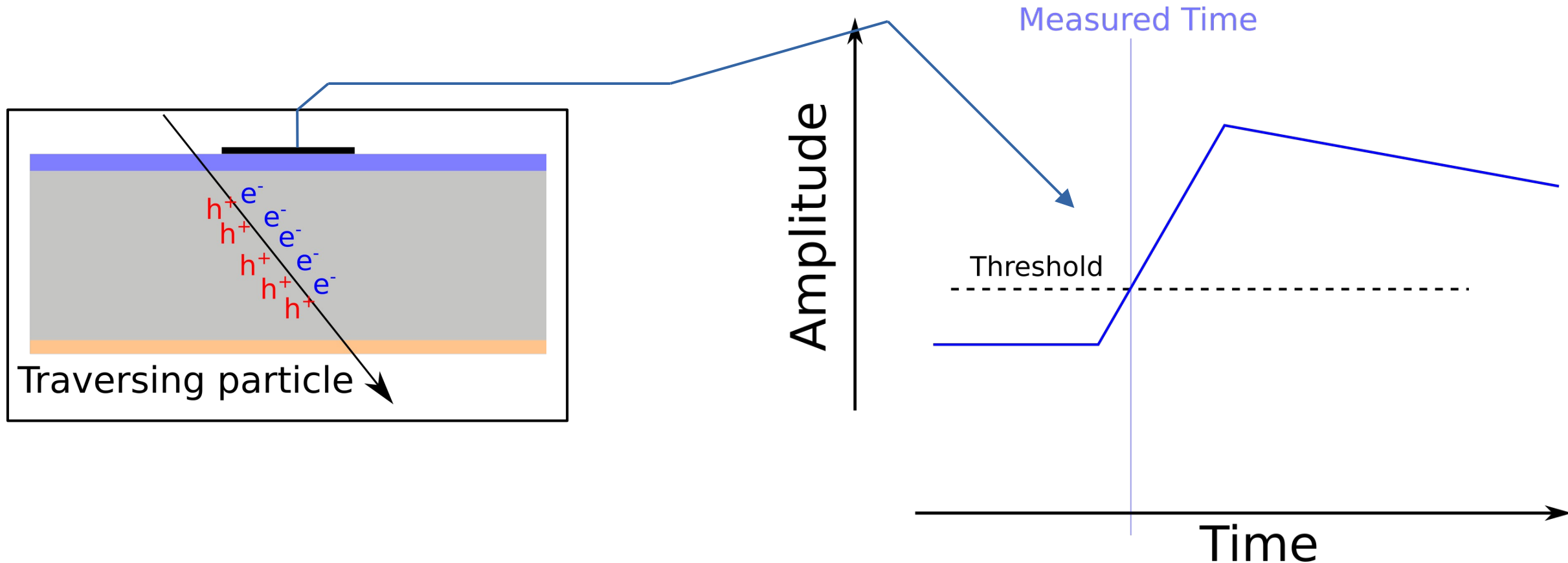
Inaccuracy of the clock and clock jitter

Time digitization error (binning error)



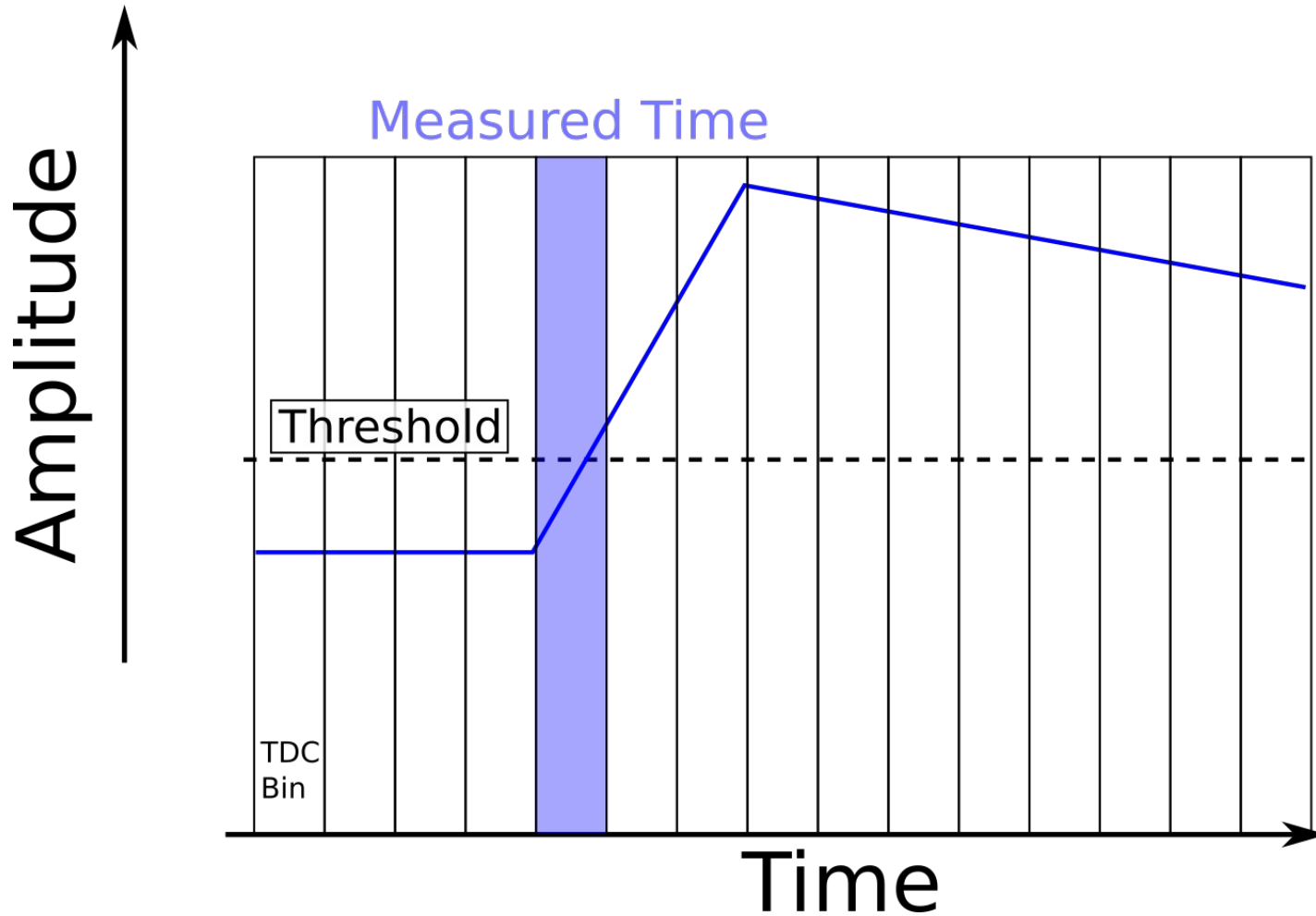
What is actually measured

- Measured is the time when a gathered charge signal crosses a threshold



Contributions to time resolution

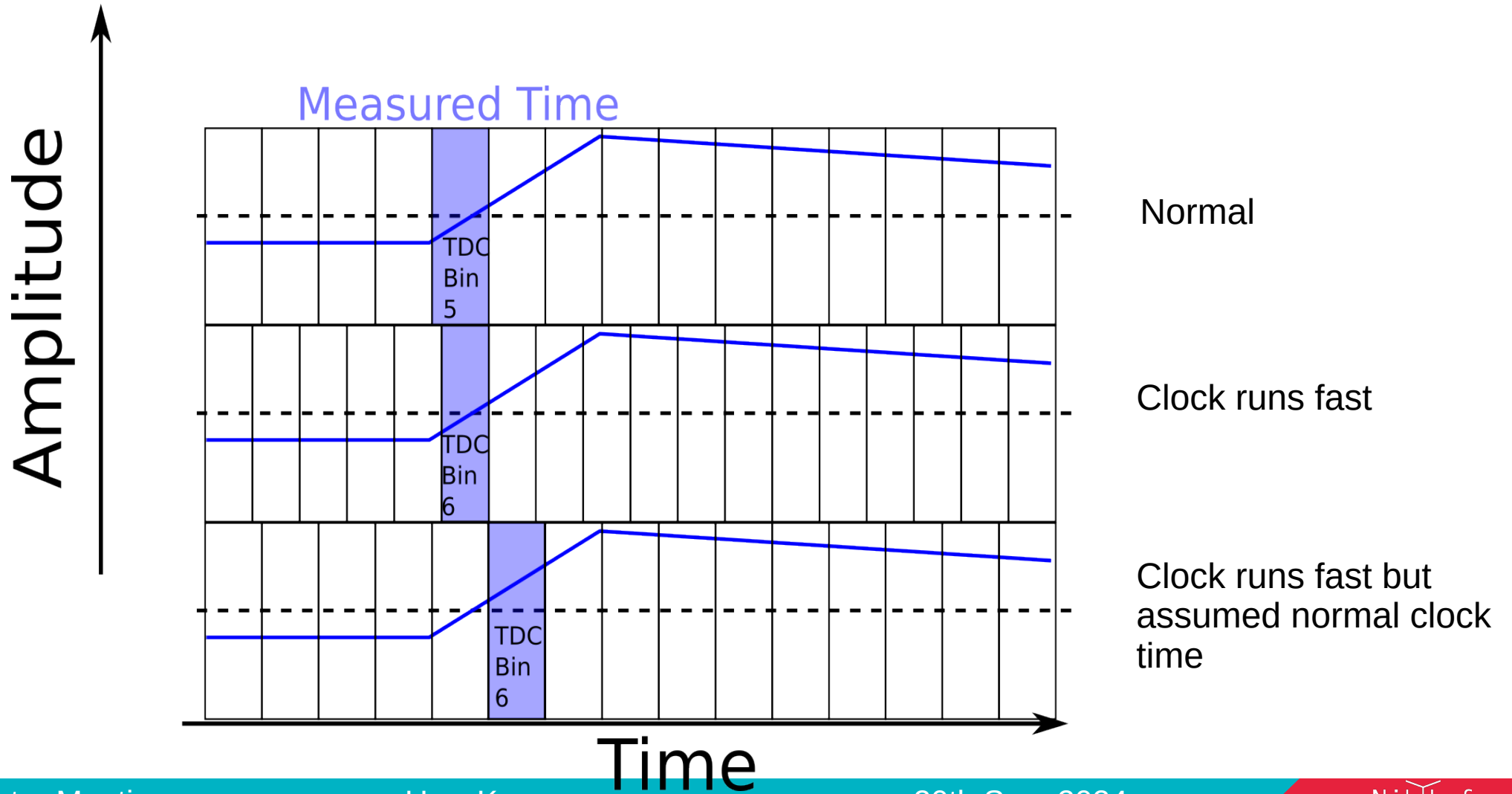
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Contributions to time resolution

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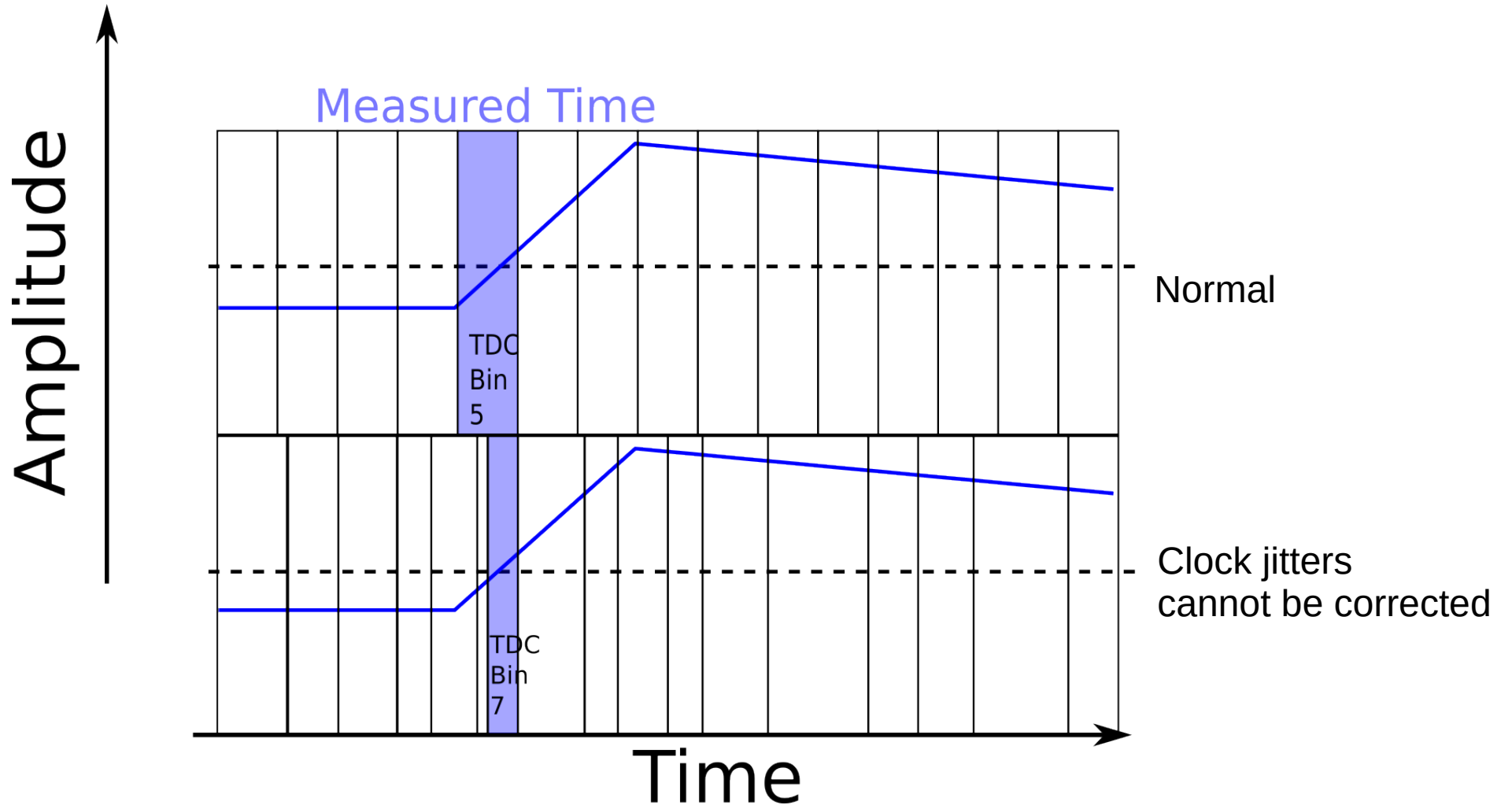
Can be partially corrected using large datasets



Contributions to time resolution

$$\sigma_t^2 = \sigma_{\text{clock-global}}^2 + \sigma_{\text{clock-on-chip}}^2 + \sigma_{\text{TDC}}^2 + \dots$$

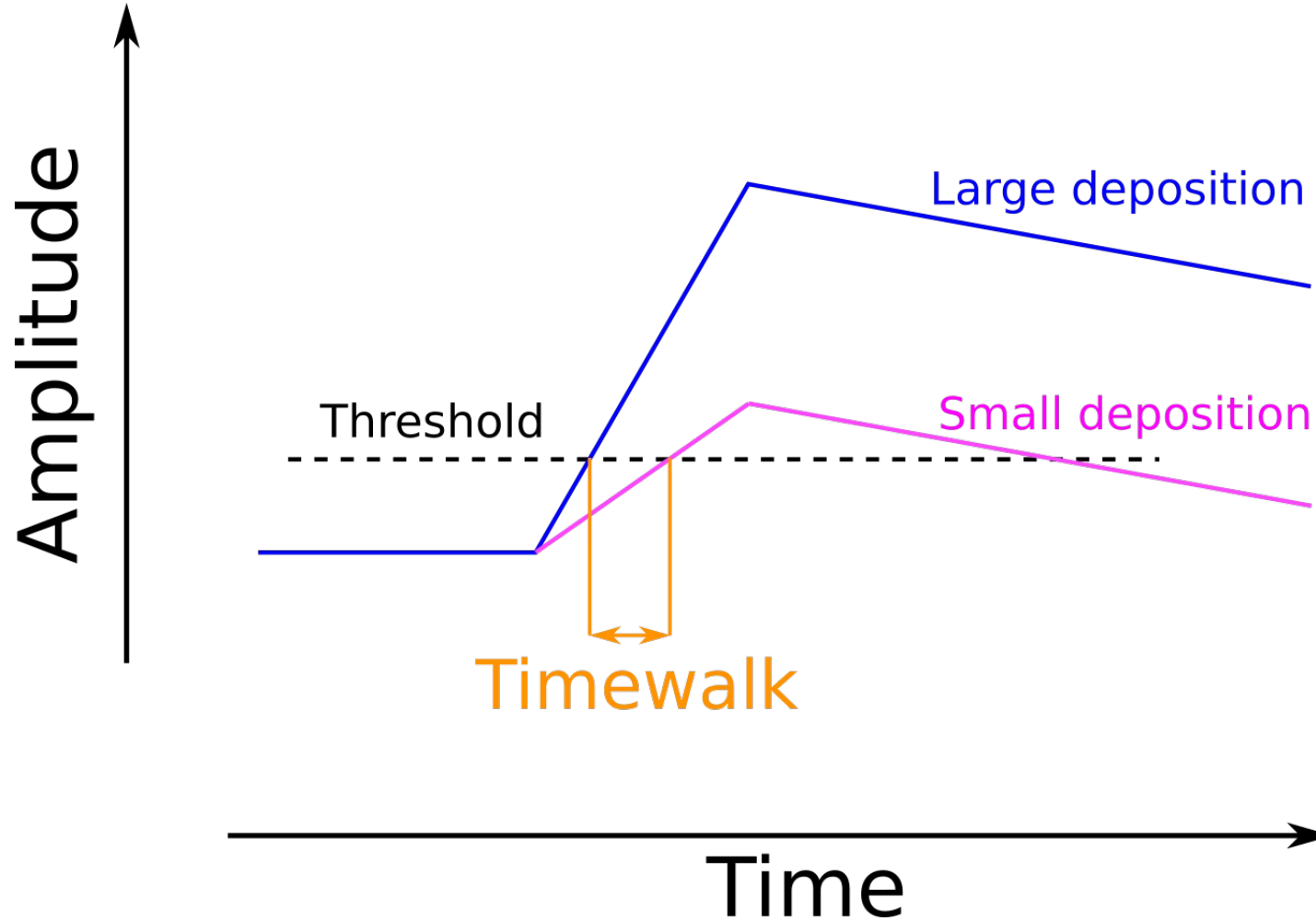
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Contributions to time resolution

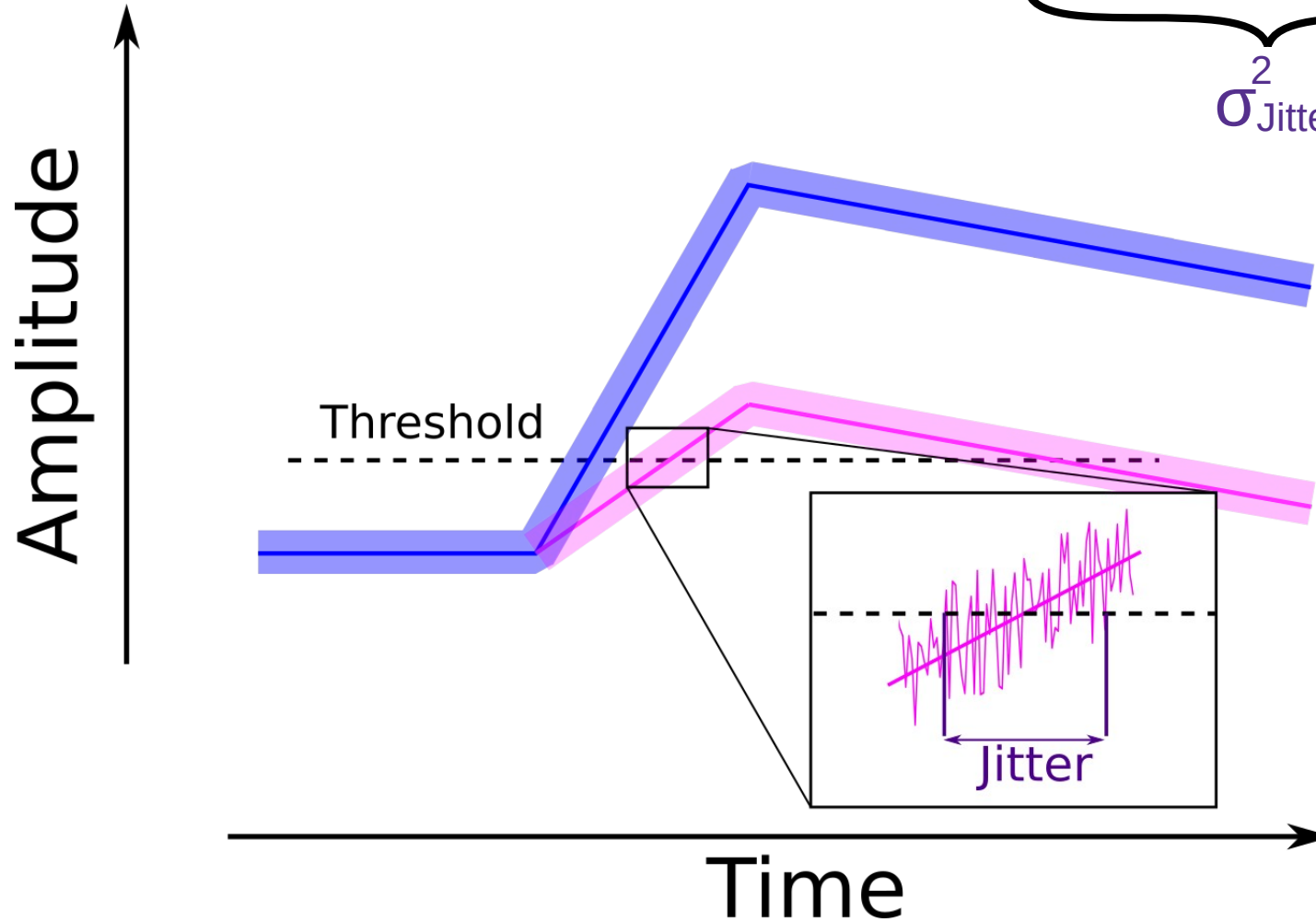
$$\sigma_t^2 = \sigma_{\text{clock-global}}^2 + \sigma_{\text{clock-on-chip}}^2 + \sigma_{\text{TDC}}^2 + \sigma_{\text{Timewalk}}^2 + \dots$$

Can be corrected
with charge
measurement



Contributions to time resolution

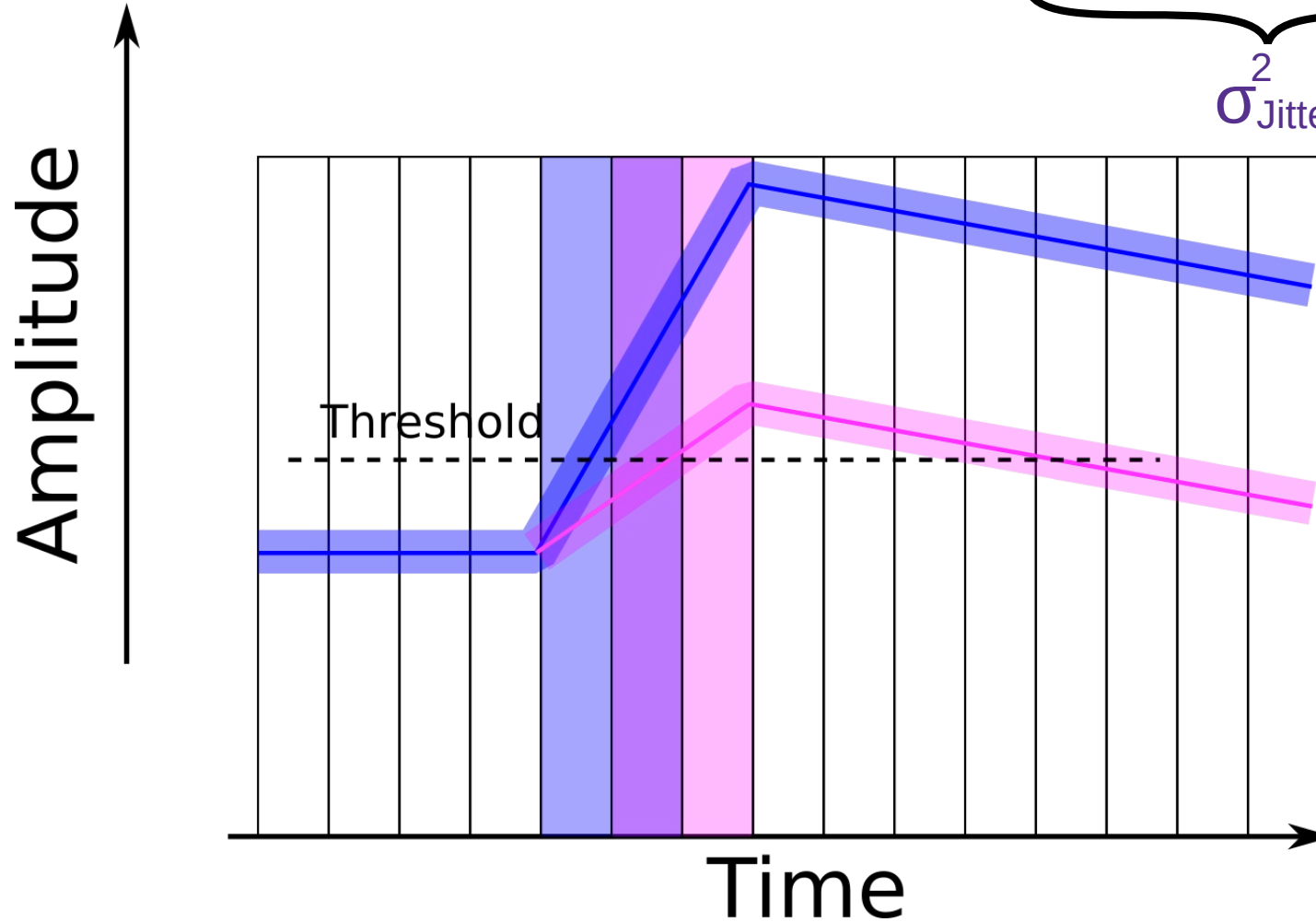
$$\sigma_t^2 = \sigma_{\text{clock-global}}^2 + \sigma_{\text{clock-on-chip}}^2 + \sigma_{\text{TDC}}^2 + \sigma_{\text{Timewalk}}^2 + \underbrace{\sigma_{\text{Landau}}^2 + \sigma_{\text{Front-end}}^2}_{\sigma_{\text{Jitter}}^2}$$



σ_{Jitter}^2 ← Can be minimized by sensor geometry, capacitance etc.

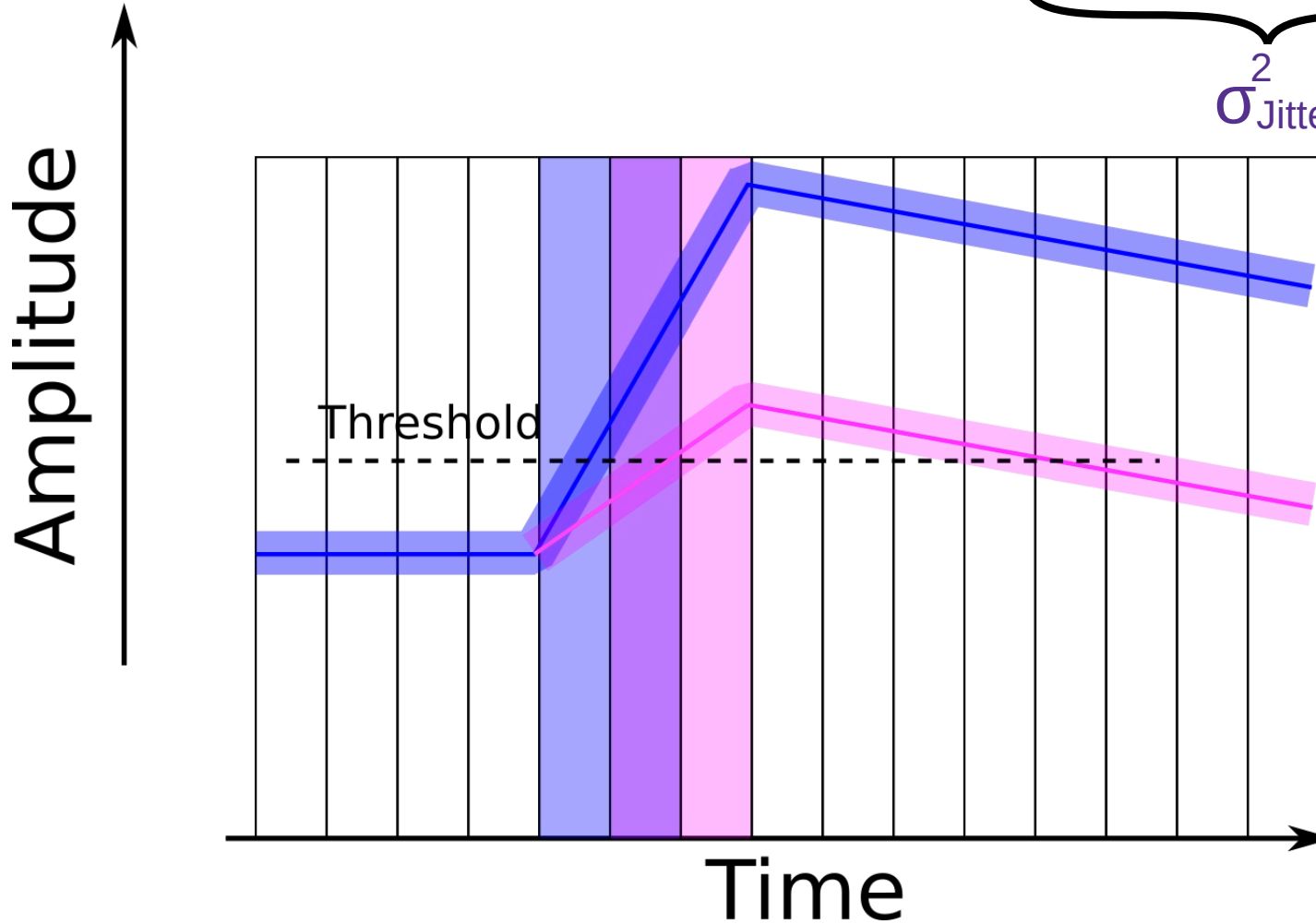
Contributions to time resolution

$$\sigma_t^2 = \sigma_{\text{clock-global}}^2 + \sigma_{\text{clock-on-chip}}^2 + \sigma_{\text{TDC}}^2 + \sigma_{\text{Timewalk}}^2 + \underbrace{\sigma_{\text{Landau}}^2 + \sigma_{\text{Front-end}}^2}_{\sigma_{\text{Jitter}}^2}$$



Contributions to time resolution

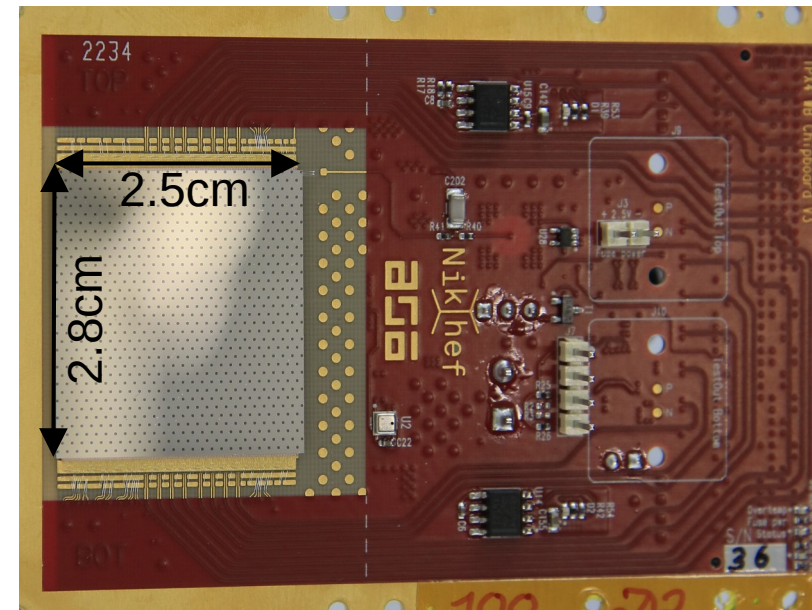
$$\sigma_t^2 = \sigma_{\text{clock-global}}^2 + \sigma_{\text{clock-on-chip}}^2 + \sigma_{\text{TDC}}^2 + \sigma_{\text{Timewalk}}^2 + \underbrace{\sigma_{\text{Landau}}^2 + \sigma_{\text{Front-end}}^2}_{\sigma_{\text{Jitter}}^2} (+ \sigma_{\text{Pixel-to-Pixel}}^2)$$



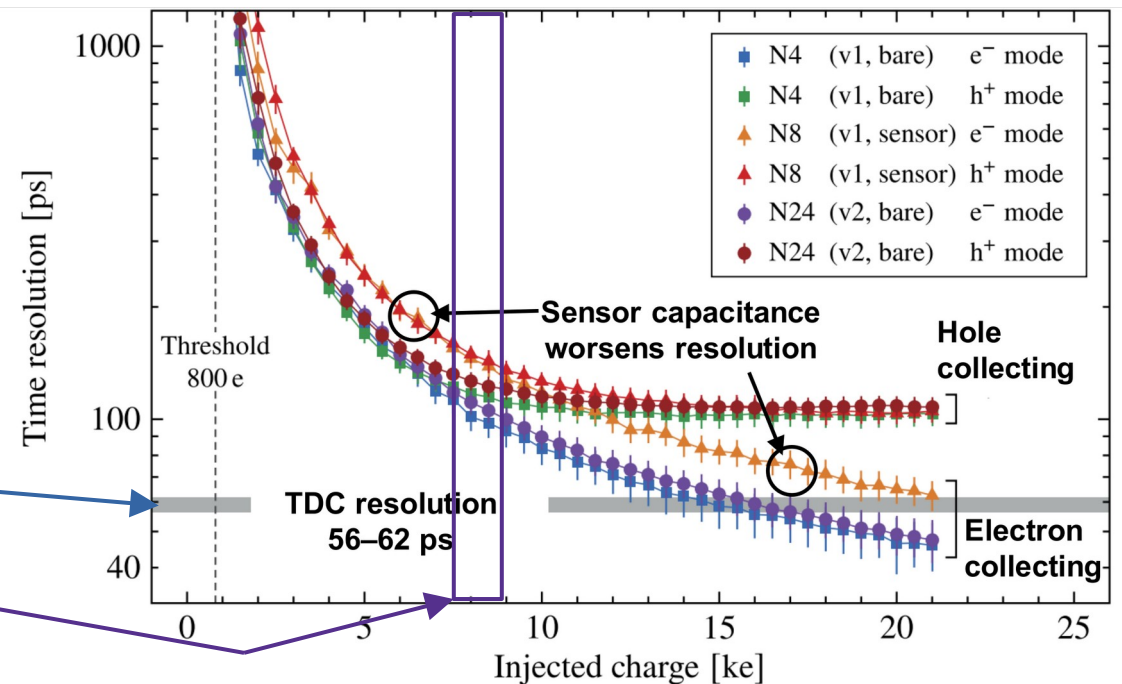
Removed through calibration, requires high statistics

Moving beyond digital limits

- Older ASICs
 - Timepix3 $\sigma_{\text{TDC}} \sim 450$ ps
- Newer ASICs
 - **Timepix4 $\sigma_{\text{TDC}} \sim 62$ ps**
- Next goal:
 - Picopix $\sigma_{\text{TDC}} < 20$ ps



- Impact of other contributions begin to be significant
 - Only capacitive load from sensor
 - **$\sigma_{\text{Front-end}} \sim 100$ ps**

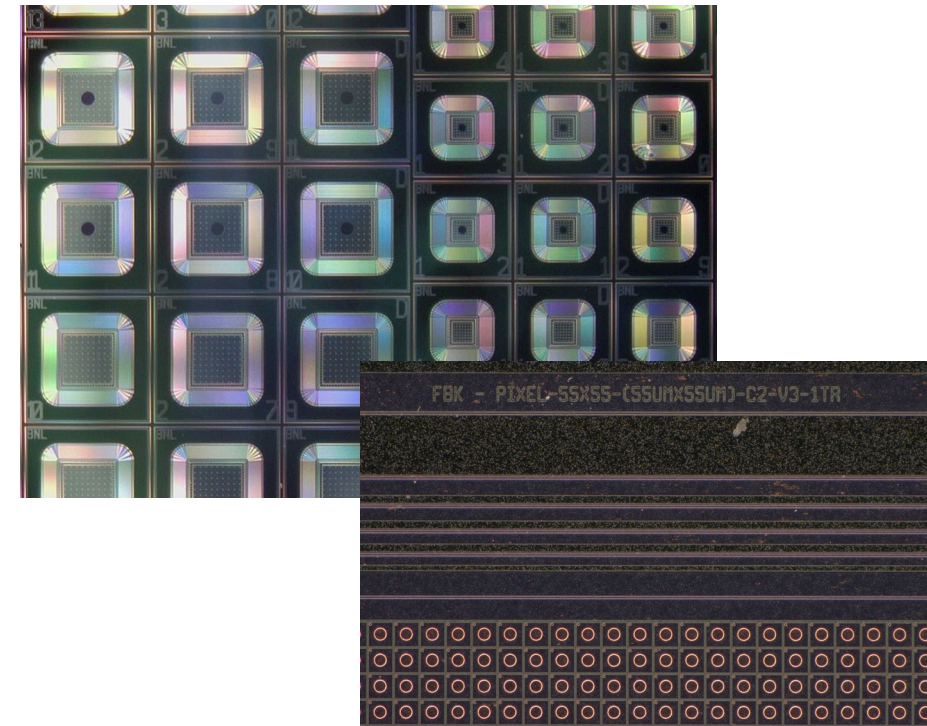
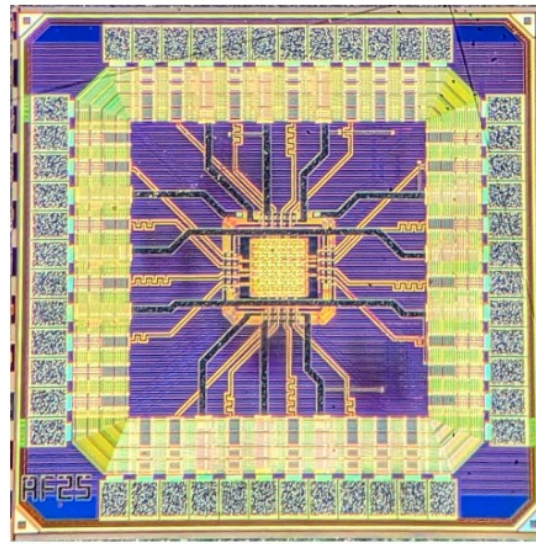
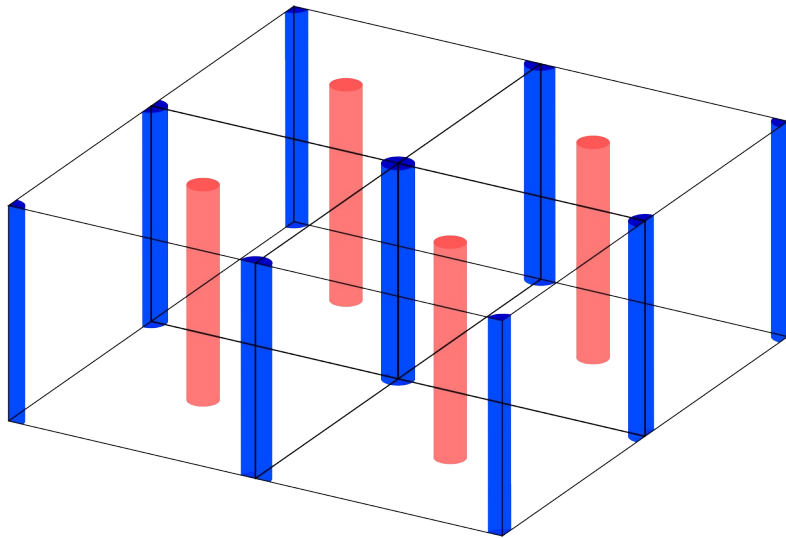


Improving Fast Timing



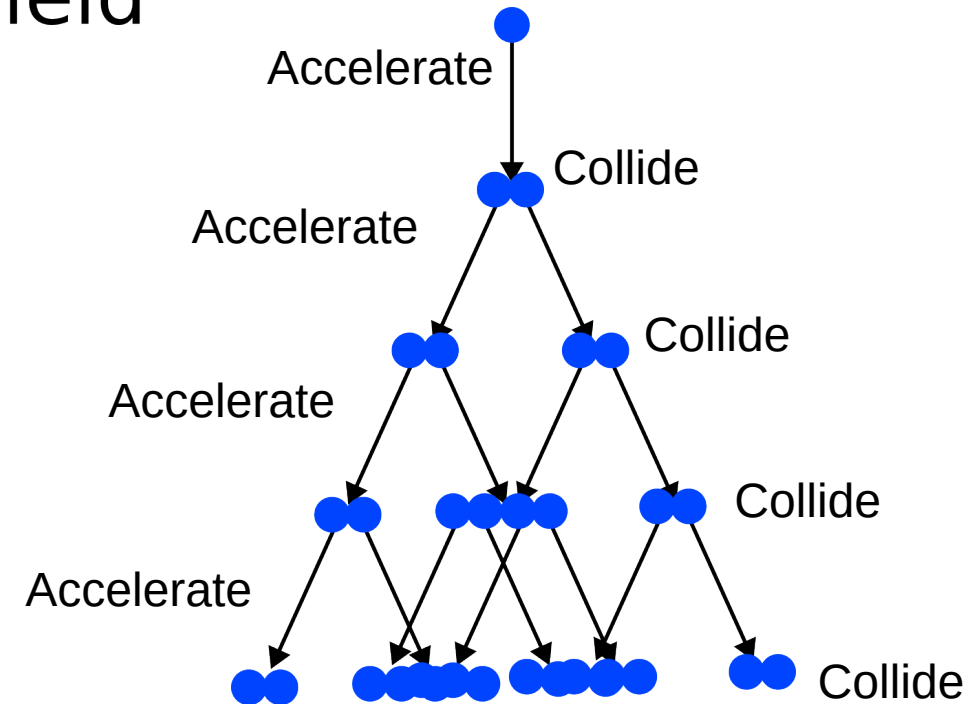
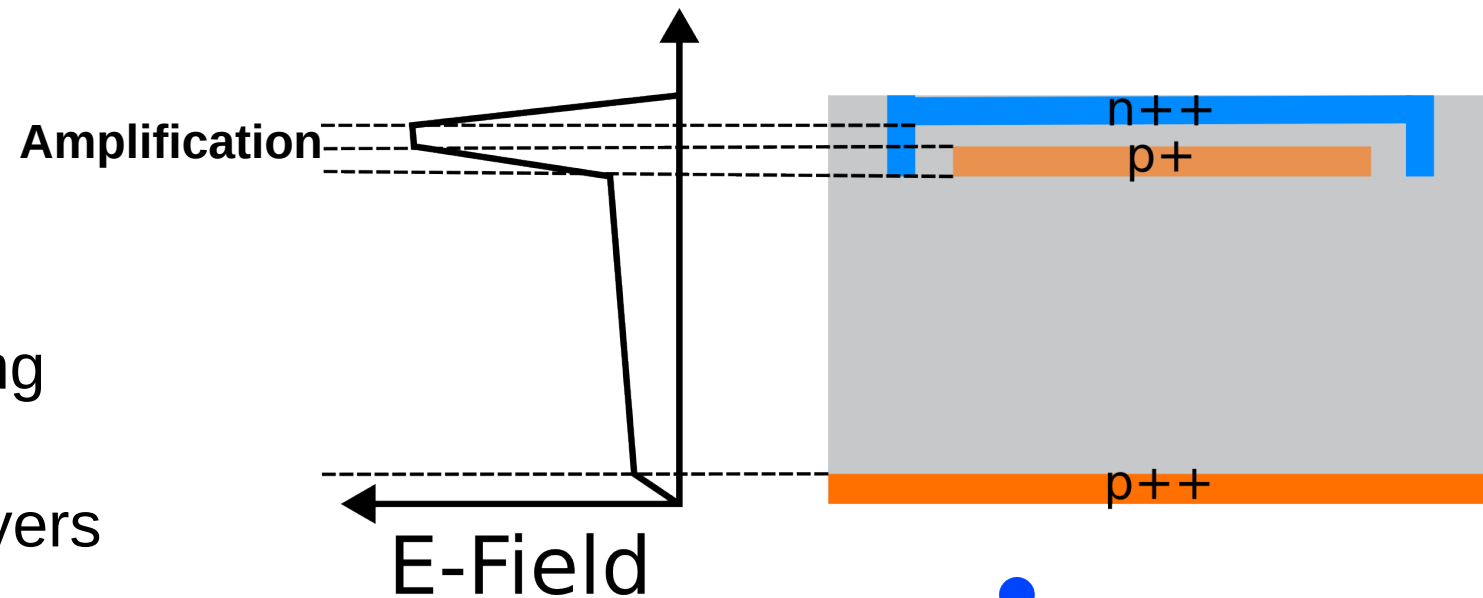
Different Approaches to Fast Timing Sensors

- Decision on what to improve/prioritize drives different sensor designs
- 3D sensors
 - Large signal generation
 - ...
- Monolithic Active Pixel Sensors (MAPS)
 - Low capacitance
 - ...
- Low Gain Avalanche Detectors (LGAD)
 - In-sensor amplification
 - ...



Gain in sensors

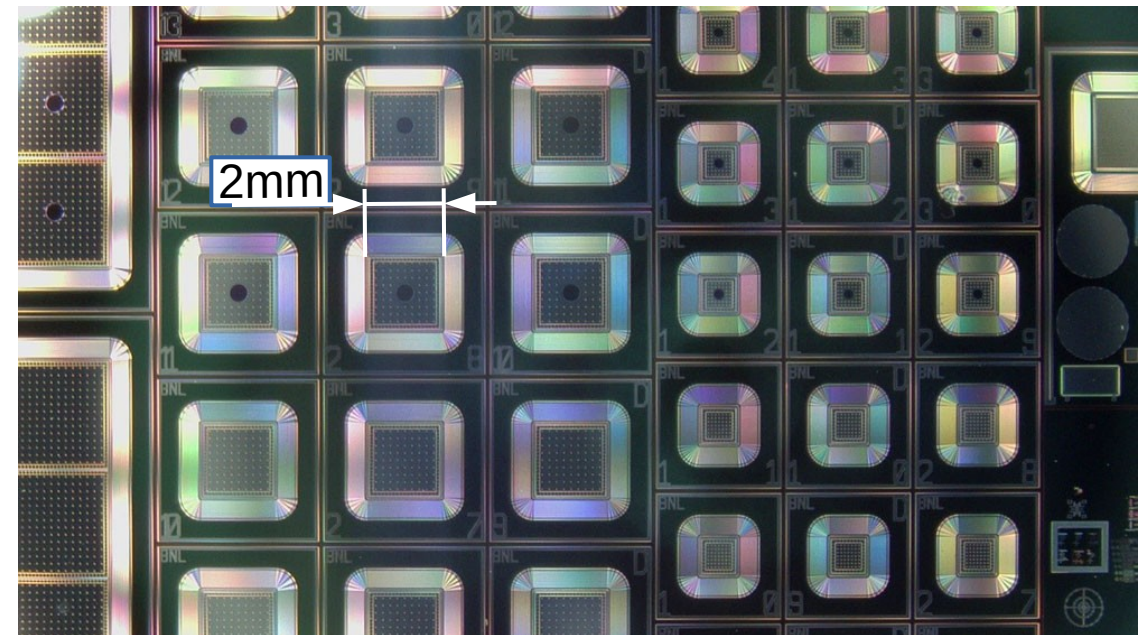
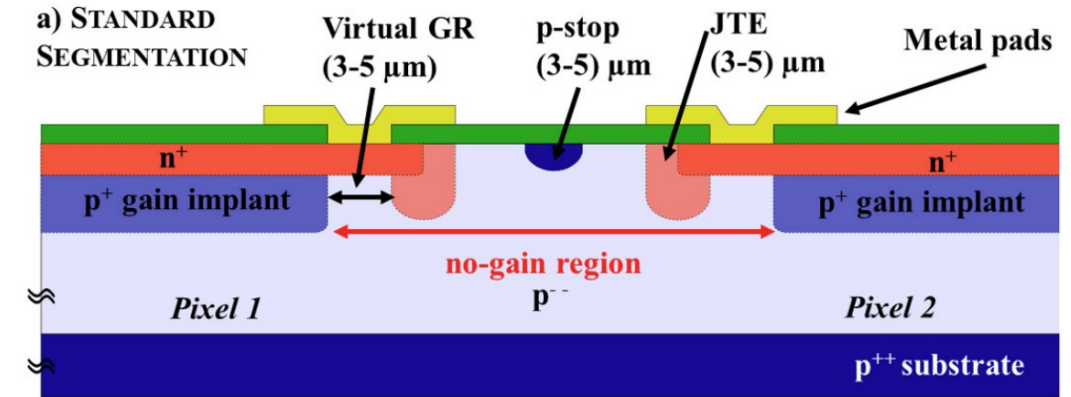
- Electron-hole pairs produced by collisions with charged particles
- Can we induce this with the drifting charge? Yes!
 - Adding specific highly doped layers produces a strong electric field
 - Electrons accelerate enough to produce more Electron-hole pairs via collisions
 - Cascading effect until field reduces
 - Position of layer, doping concentration etc. all influence gain
 - Low Gain Avalanche = $O(10)$



LGAD Pixel (Standard)

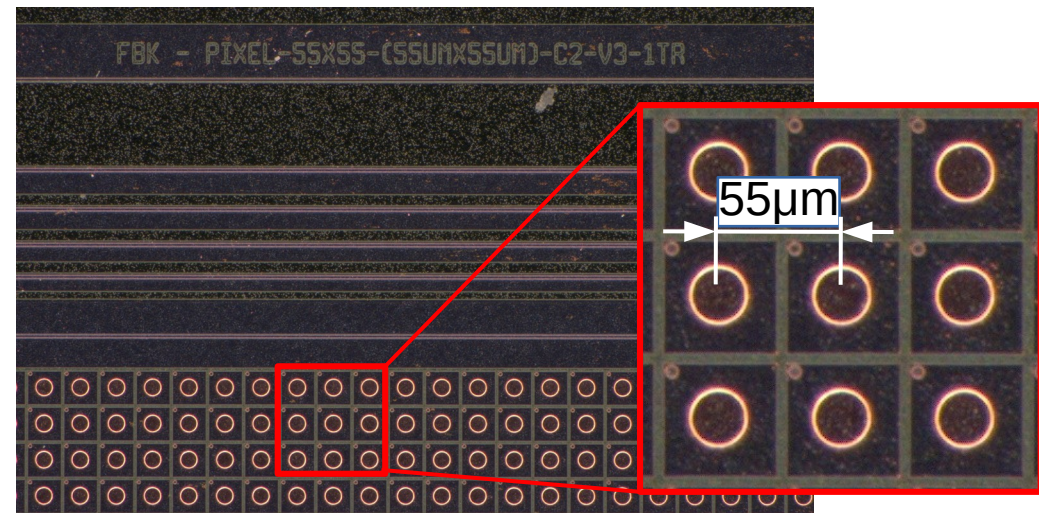
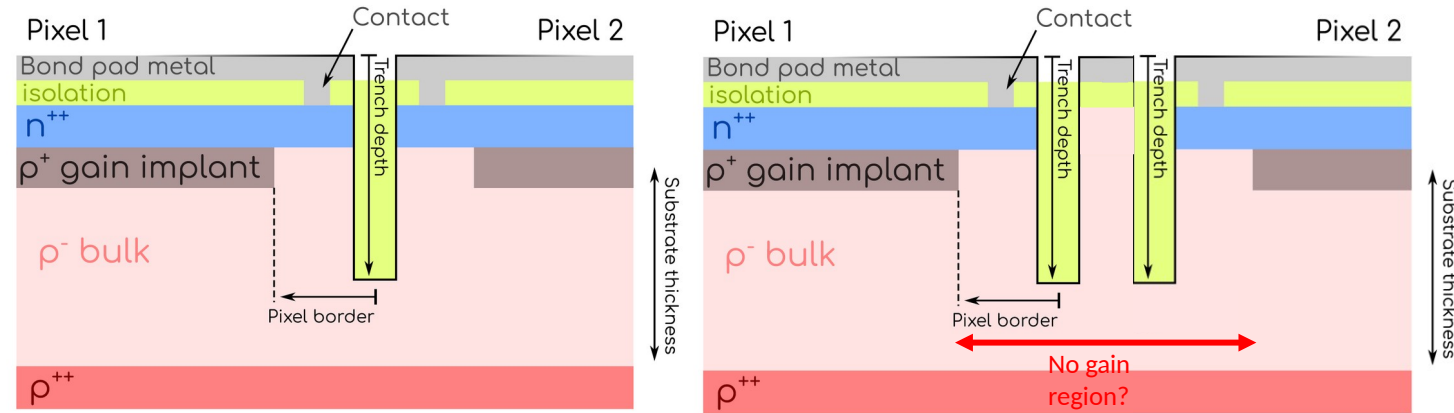
- Gain implants require electrical isolation and
 - Region without gain $O(100 \mu\text{m})$
 - Large pixels to reach high fraction of active region (Fill Factor)
- Large pixels with great timing
- Excellent for timing layers
 - Insignificant spatial resolution
 - Not usable for 4D tracking

Can we make the isolation somehow smaller?



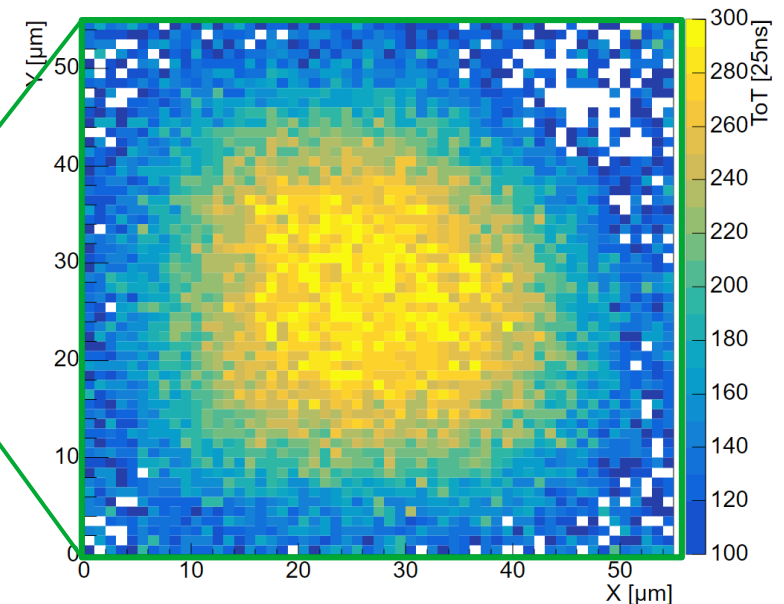
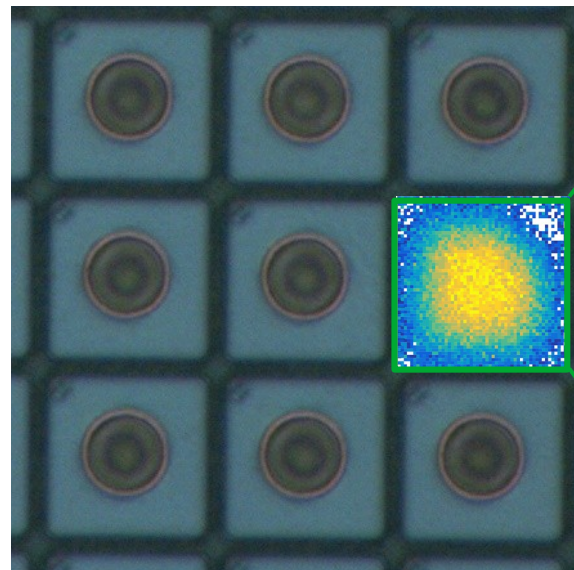
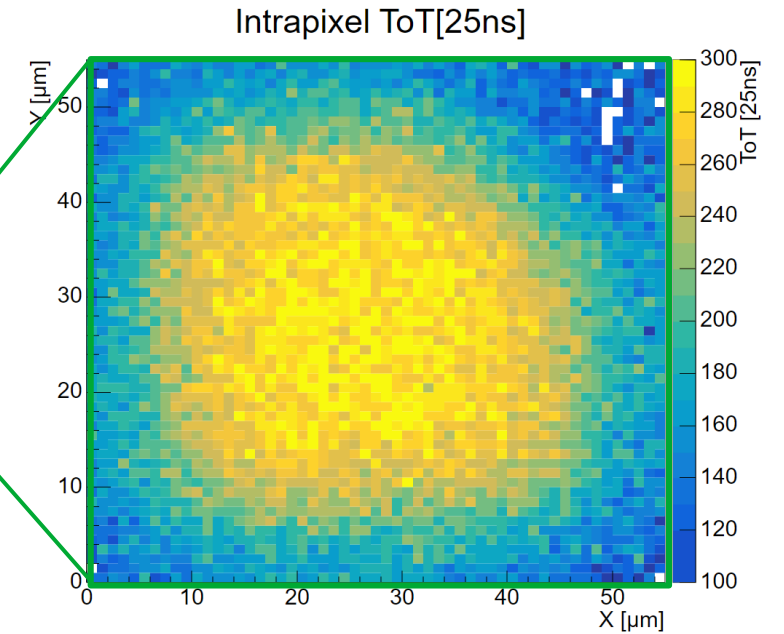
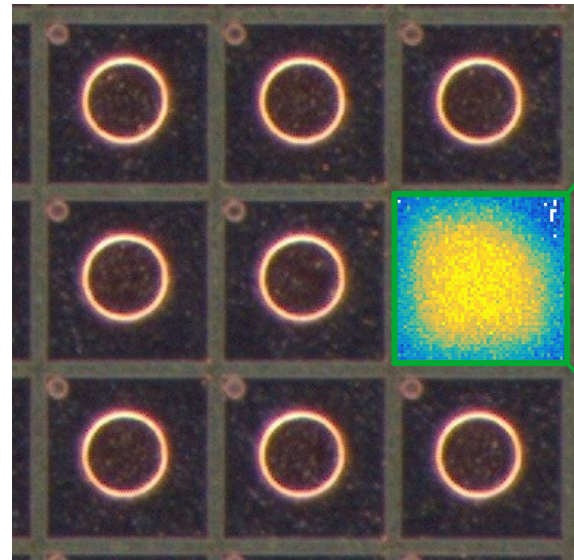
LGAD Pixel (Trenches)

- Cutting one or multiple gaps into silicon
 - Filled with silicon oxide as isolation
- Trench width and distance to gain implant $\sim O(1\mu\text{m})$
 - Small pixels possible (55 μm pitch)
- Devices installed on TPX4 ASIC.
 - First small pixel LGAD with fully integrated readout



Testing of Trench-Isolated-LGAD (TI-LGAD)

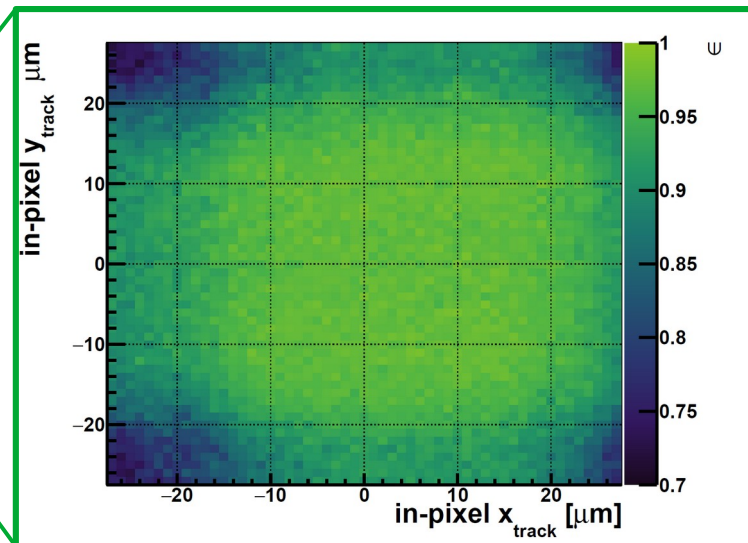
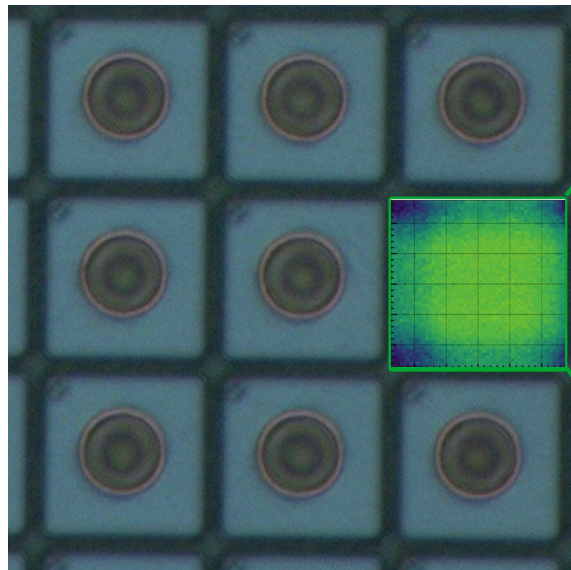
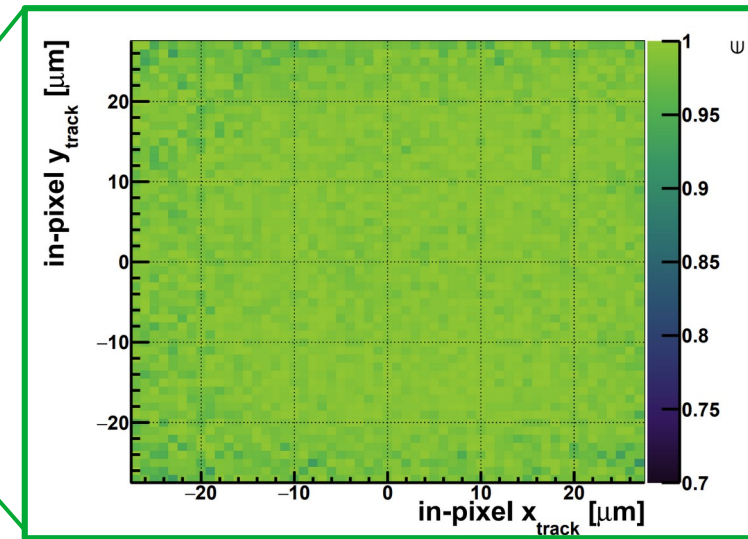
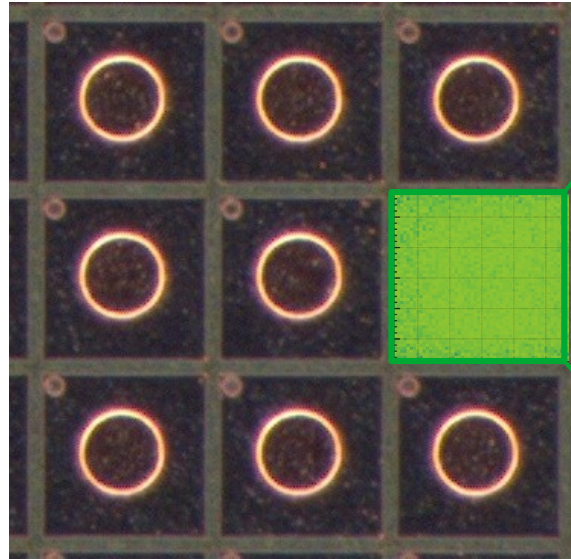
- Investigation into in-pixel structures
 - Area close to the trenches
- Both devices show reduced gain towards the edges



Testing of Trench-Isolated-LGAD (TI-LGAD)

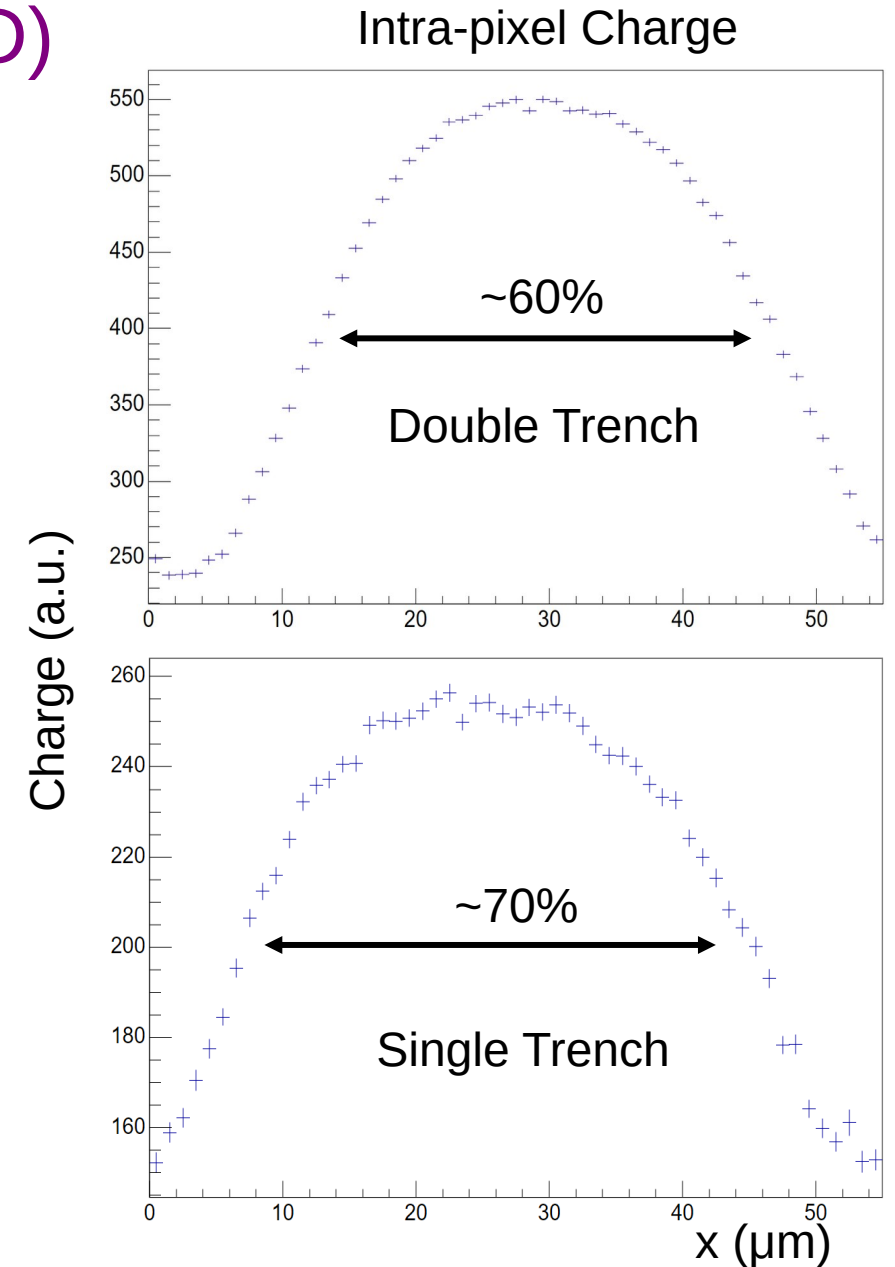
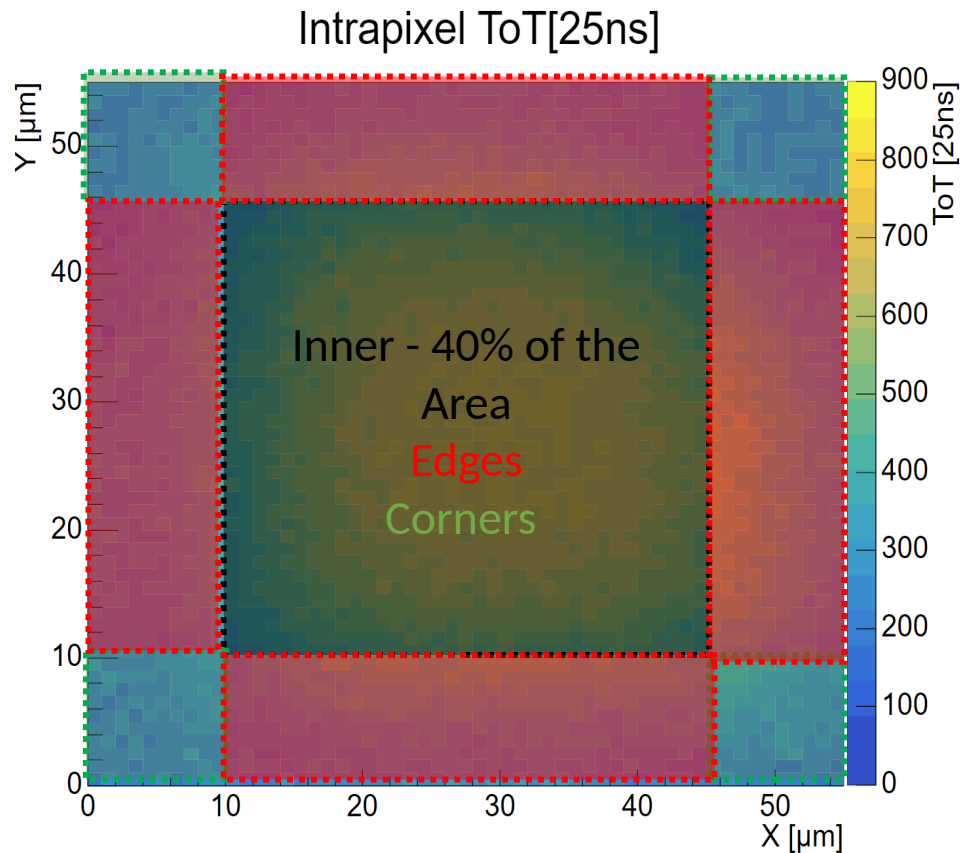
- Investigation into in-pixel structures
 - Area close to the trenches
- Both devices show reduced gain towards the edges
- Double trench device has efficiency drop in the corners

- Lowers effective Fill Factor and usable area to the center



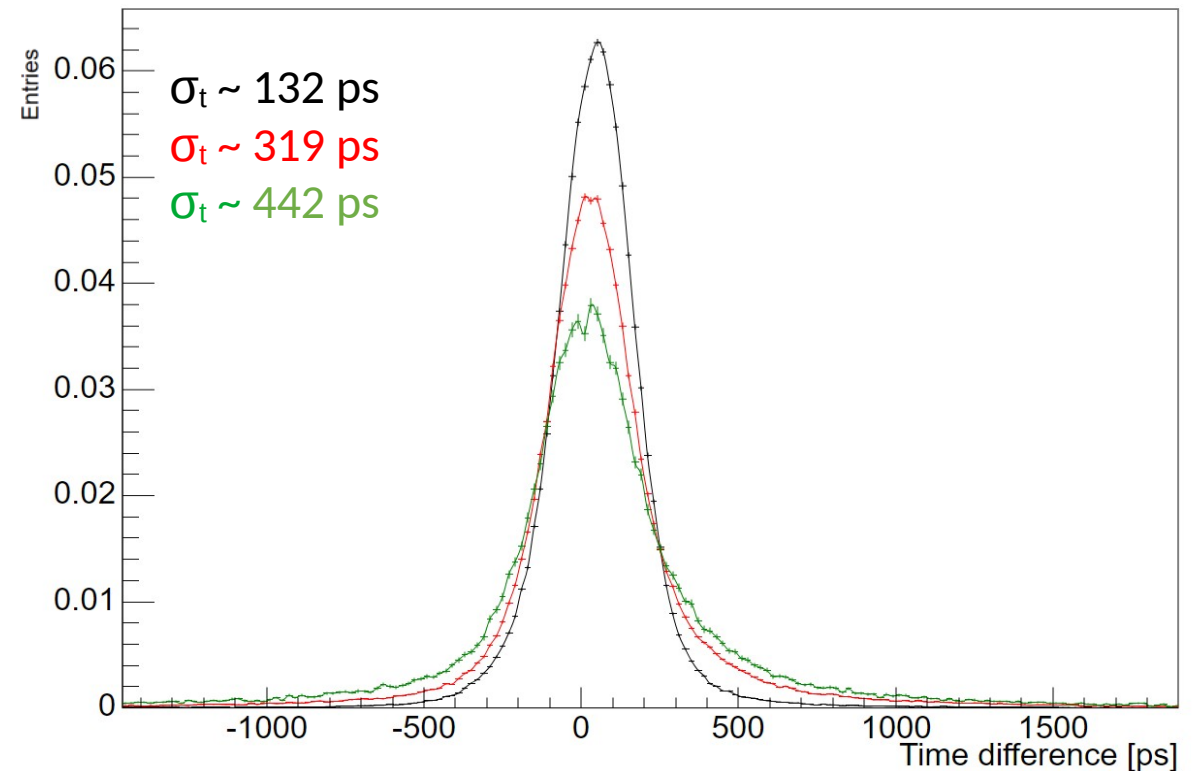
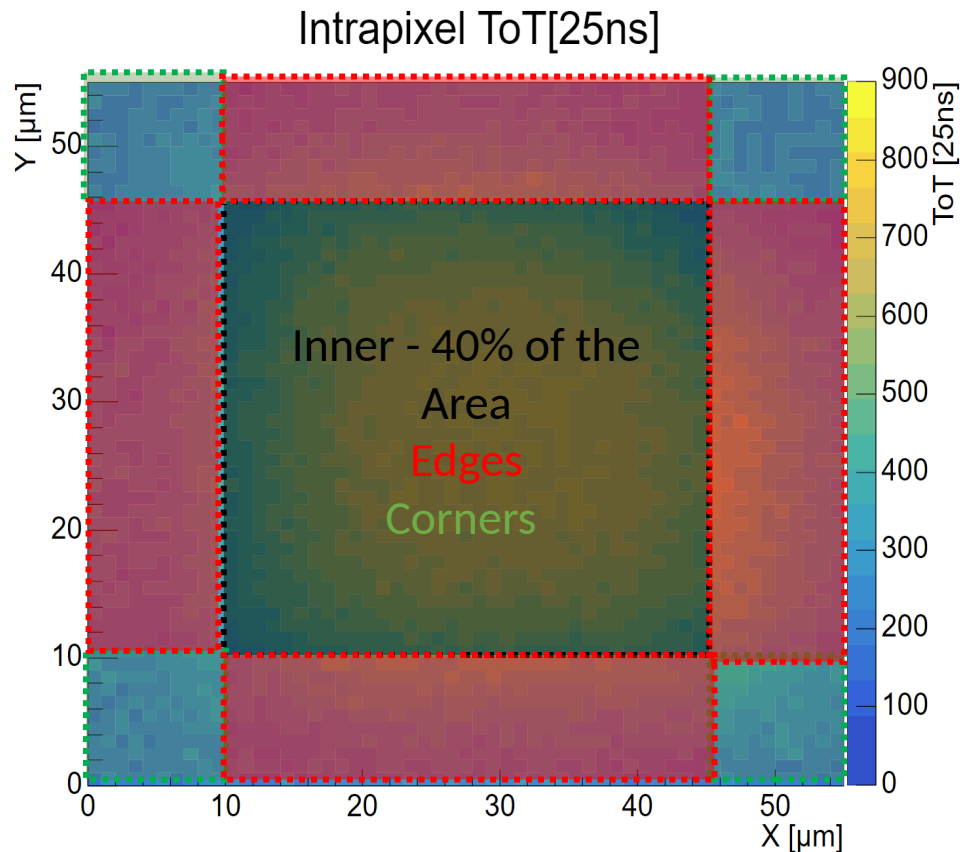
Testing of Trench-Isolated-LGAD (TI-LGAD)

- Only 60/70% area with decent gain for (single/double trench)



Testing of Trench-Isolated-LGAD (TI-LGAD)

- Time resolution varies a lot between the different areas inside the pixel
- Limiting data to the central area reaches a time resolution of **132 ps** before clock corrections for the double trench



Conclusion and Outlook

- Timing requirements have increased by ~ 1000 .
- Timing itself has many aspects and levers for optimization that interplay with one another.
- Small pixel TI-LGAD can achieve excellent time resolution. Without clock correction $O(130 \text{ ps})$ with full integration.
- Issues with gain towards pixel edges reduces effective area.
- Unexpected loss of efficiency for double trench device at the corners.
 - Hope to achieve sub 100 ps time resolution in central area.
 - Investigate and optimize area with good gain performance.

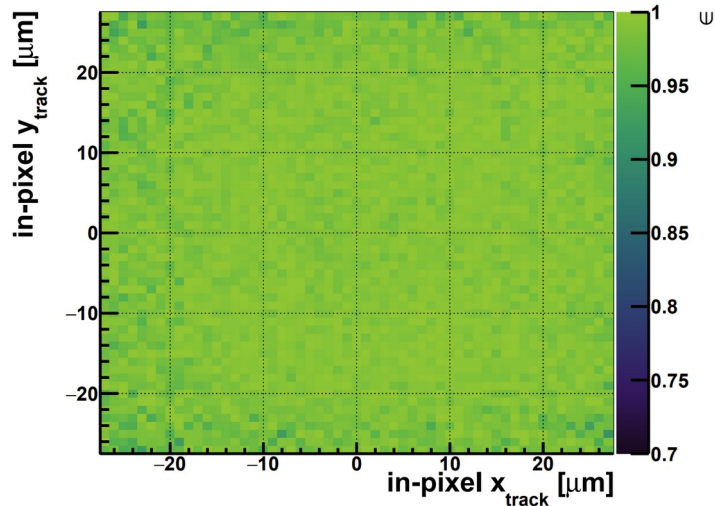
Backup slides

Trench comparison with planar

- Loss of efficiency in double trench not visible in single trench
- Also not visible in the planar sensor
- Unknown what causes this. Some ideas as to the cause, to be investigated

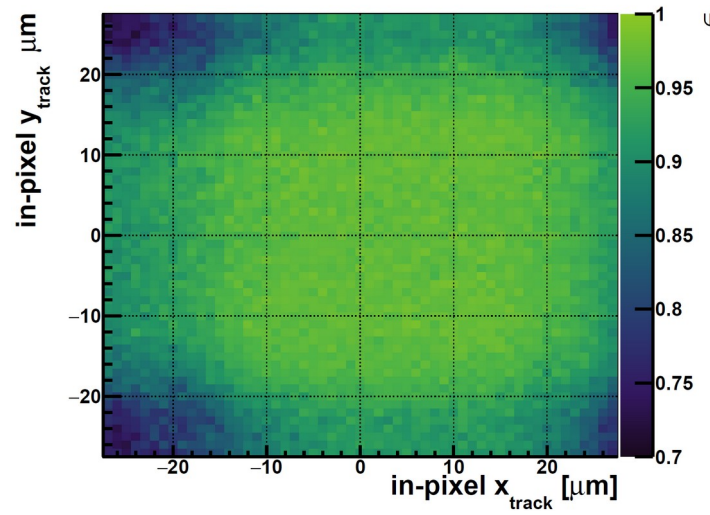
Single trench - 100V

Average ~ 97%



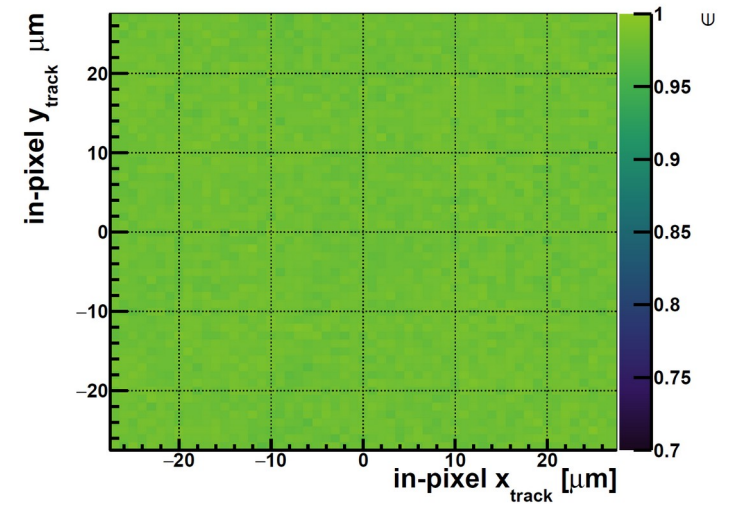
Double trench - 200V

Average ~ 93%



Reference 50 μm planar - 60V

Average ~ 97%



Signal rise time

- Jitter depends on front-end noise and therefore capacitance
- For the same amount of noise a fast rising signal is impacted less for its time resolution

